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IN THE SPECIFICATION:

Please amend the specification with the replacement paragraphs as follows:

[0018] Figure 5 shows one embodiment of the invention in flowchart form. More specifically, as shown in item 50, the invention begins by attaching the device to the electrostatic chuck pins. Next, in item 52, the invention measures the flatness of the device. In item 53 54, the invention adjusts the height of the height adjustment mechanisms that are connected between the electrostatic chuck pins and the plate of the electrostatic chuck, to correct any flatness errors determined in the measuring process. This adjusting process can adjust each height adjustment mechanisms individually and can be performed using the computer connected to the measurement device and to the height adjustment mechanisms. As mentioned above, the adjusting process compensates for foreign matter particles between the electrostatic chuck pins and the device being held by the electrostatic chuck pins, and changes the shape of the device to conform to a pre-existing standard.